Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

HP EliteDesk 705 G1 DM Business PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 **Items Requiring Selective Treatment**

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Chicony Power - A120A01CH</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Chicony Power - A120A01CH</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>#1 Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>#2 Torx Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>#3 Slotted Screwdriver</td>
<td>2</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

2.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disconnect the AC adapter cable.(see Figure 1 below)
2. Remove the access panel.(see Figure 2-3 below)
3. Remove the front bezel.(see Figure 4-5 below)
4. Remove HDD and HDD cable.(see Figure 6-9 below)
5. Remove HDD cage and Hood sense cable.(see Figure 10-12 below)
6. Remove Memorys.(see Figure 13-14 below)
7. Remove CPU HeatSink.(see Figure 15-16 below)
8. Remove system fan.(see Figure 17-19 below)
9. Remove PCIE cards.(see Figure 20-24 below)
10. Remove speaker,CPU and battery.(see Figure 25-31 below)
11. Remove MB.(see Figure 32-33 below)
12. Remove antenna cover and antenna cables.(see Figure 34-38 below)
13. The tool used for detaching external adapter is showing in figure 39.
14. Cut the join corner of external cover using Micro shear(Tool #1).(see Figure 40~41 below)
15. Separated the plastic covers.(see Figure 42)
16. Cut out the shielding soldered points using Micro shear(Tool #1), separated the shielding.(see Figure 43)
17. Remove a biggest E-cap using Micro shear(Tool #1),(see Figure 44)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
PSG instructions for this template are available at EL-MF877-01
PSG instructions for this template are available at [EL-MF877-01](#).
Figure 13: Loose the fixed feature of memory.

Figure 14: Remove the Memory from the board.

Figure 15: Loose the screw of CPU HeatSink.

Figure 16: Remove the CPU HeatSink.

Figure 17: Disconnect the system fan cable.

Figure 18: Loose the screws of system fan cable.

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 19: Remove the system fan.

Figure 20: Disconnect the antenna cable.

Figure 21: Loose the WLAN card screw.

Figure 22: Remove the WLAN card.

Figure 23: Loose SSD card screw.

Figure 24: Remove the SSD card.

PSG instructions for this template are available at EL-MF877-01.
Figure 25 Disconnect the speaker cable.

Figure 26 Remove the plastic screw.

Figure 27 Remove the Speaker.

Figure 28 Rotate the handle and open it up.

Figure 29 Remove the CPU from the board.

Figure 30 Pull the battery towards the chassis wall.

PSG instructions for this template are available at EL-MF877-01
Figure 31: Remove the battery from the system board.

Figure 32: Loose MB screw.

Figure 33: Remove the MB.

Figure 34: Loose the antenna cover hook.

Figure 35: Remove the antenna cover.

Figure 36: Loose the antenna cable tape.
Figure 37: Loose the antenna hook.

Figure 38: Remove the antenna.

Figure 39: Using tools for reference.

Figure 40: Cut the join corner of external cover using Tool#1. (Use Chicony EPS as an example)

Figure 41: Continued to cut the other corners of external cover.

Figure 42: Separated the plastic cover.

PSG instructions for this template are available at EL-MF877-01
Figure 43: Cut out the shielding soldered points using Tool#1. Separated the shielding.

Figure 44: Remove a biggest E-cap using Tool#1.